

Fig. 7 GCT turn-off energy per pulse vs. turn-off current

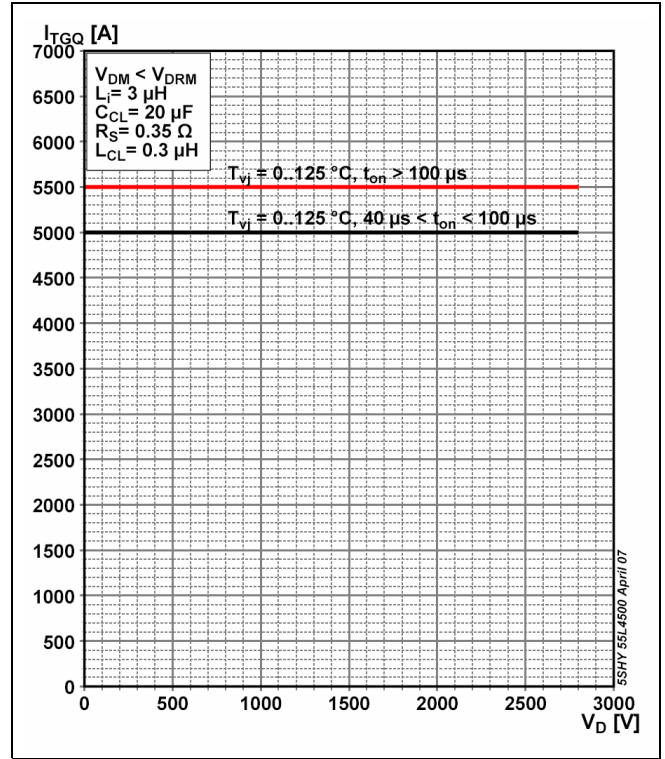


Fig. 8 Safe Operating Area

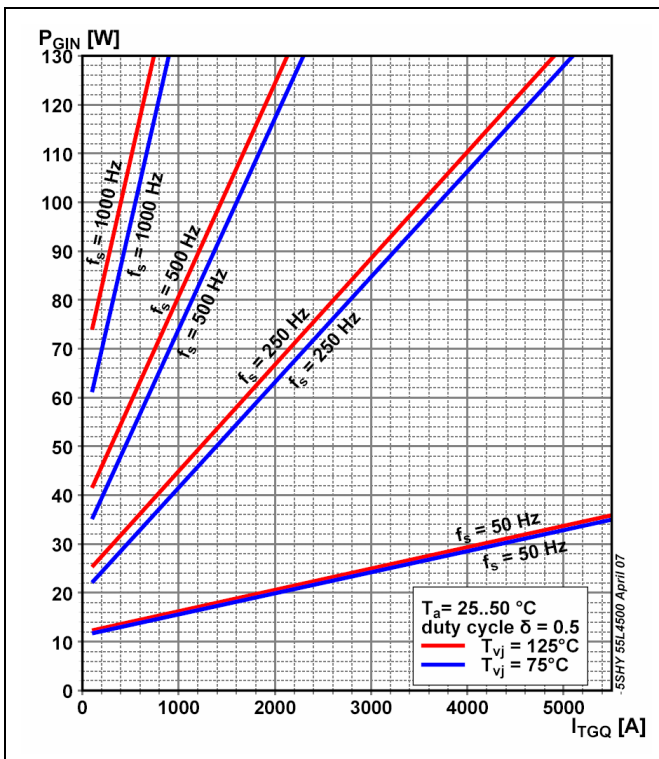


Fig. 9 Max. Gate Unit input power in chopper mode

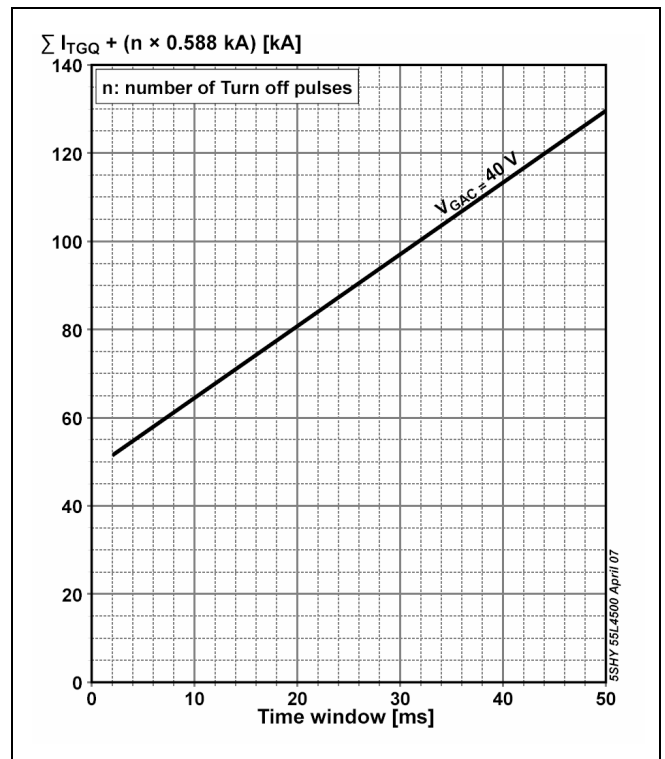


Fig. 10 Burst capability of Gate Unit

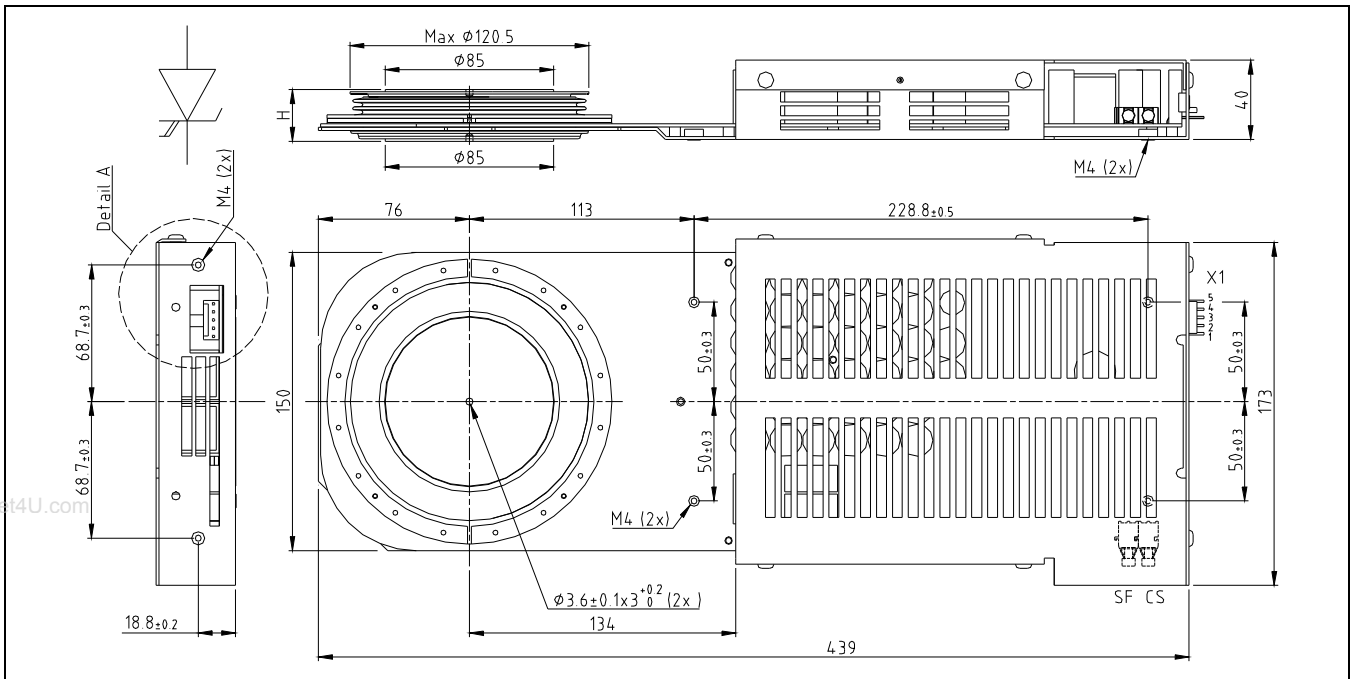


Fig. 11 Outline drawing; all dimensions are in millimeters and represent nominal values unless stated otherwise

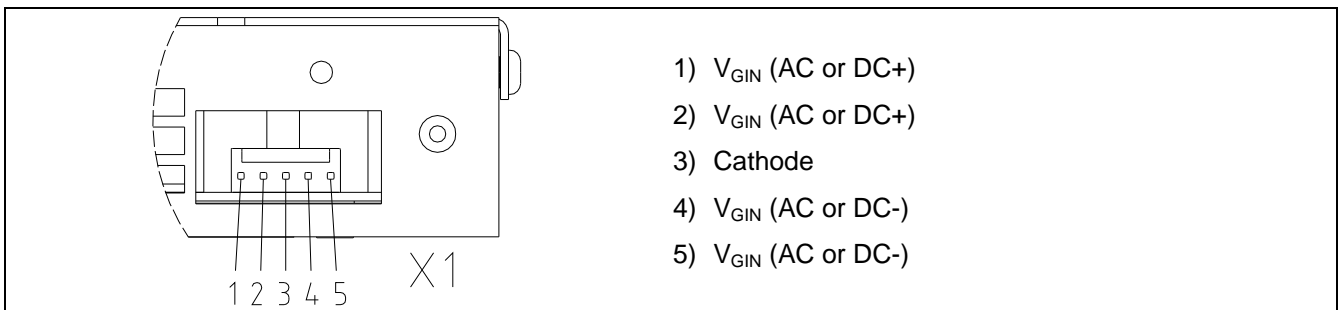


Fig. 12 Detail A: pin out of supply connector X1

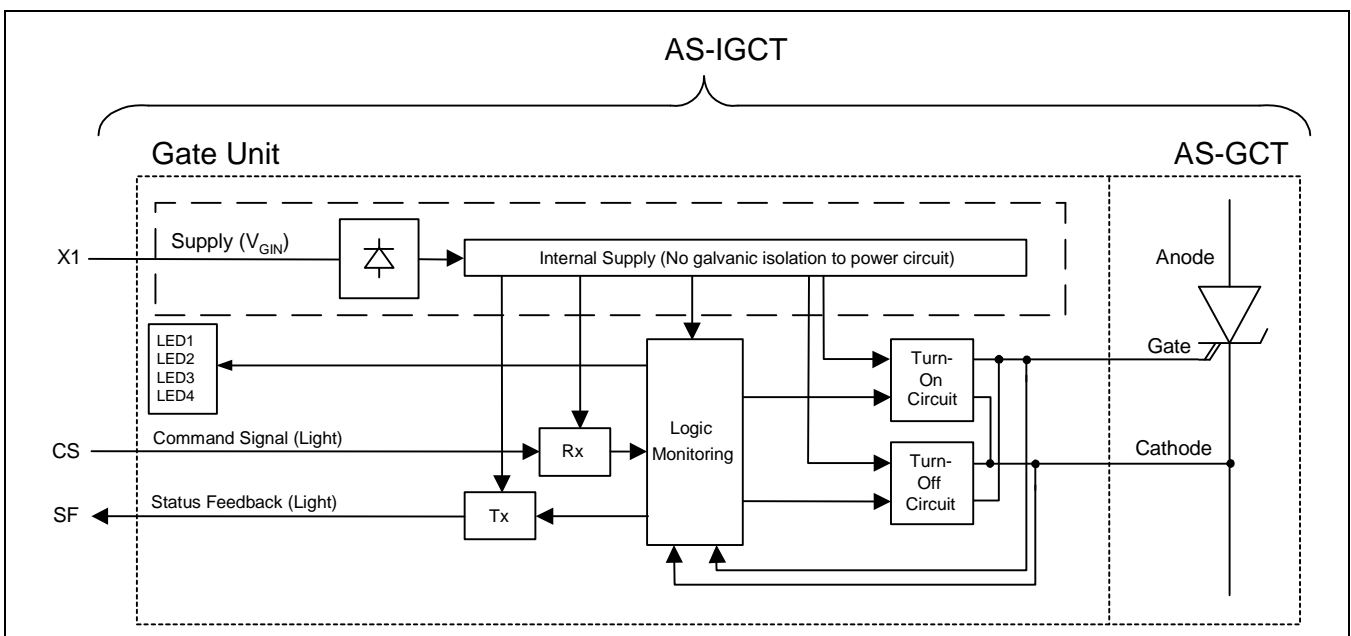


Fig. 13 Block diagram

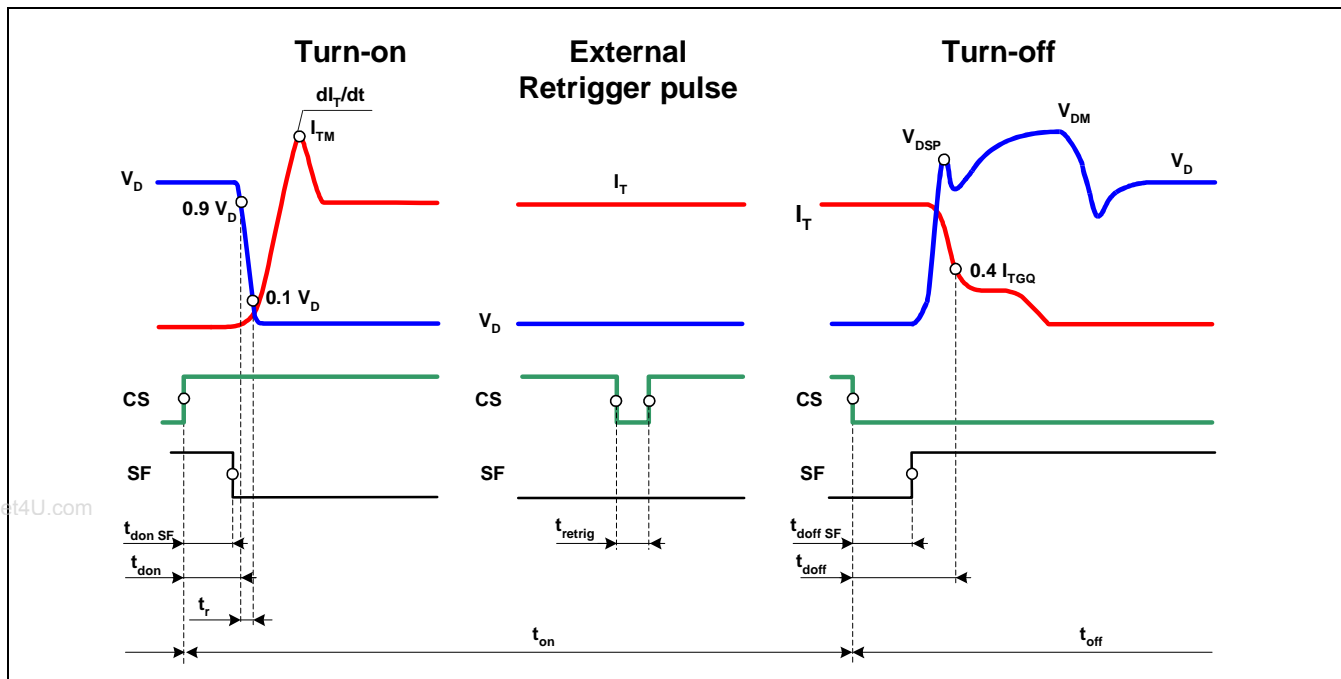


Fig. 14 General current and voltage waveforms with IGCT - specific symbols

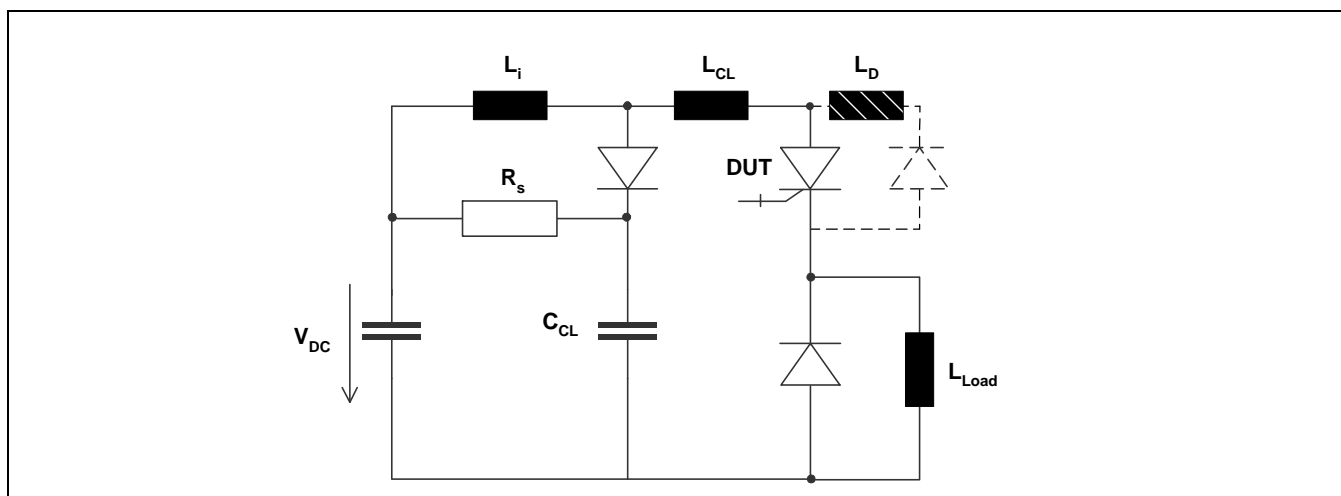


Fig. 15 Test circuit

Related documents:

5SYA 2031	Applying IGCT Gate Units
5SYA 2032	Applying IGCTs
5SYA 2036	Recommendations regarding mechanical clamping of Press Pack High Power Semiconductors
5SYA 2046	Failure rates of IGCTs due to cosmic rays
5SYA 2048	Field measurements on High Power Press Pack Semiconductors
5SYA 2051	Voltage ratings of high power semiconductors
5SZK 9107	Specification of environmental class for pressure contact IGCTs, OPERATION available on request, please contact factory

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ABB Switzerland Ltd
Semiconductors
Fabrikstrasse 3
CH-5600 Lenzburg, Switzerland

Telephone +41 (0)58 586 1419
Fax +41 (0)58 586 1306
Email abbsem@ch.abb.com
Internet www.abb.com/semiconductors